

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20160609000 Qualification of 100% Cu wire bonding on select nfBGA Devices Change Notification / Sample Request

Date: 7/1/2016

To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN www_admin_team@list.ti.com).

Sincerely,

PCN Team SC Business Services

20160609000 Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
AM1808EZCEA3	null
OMAPL138EZWT4	null
TMS320C6746EZWT4	null
AM1806EZWT3	null
TMS320C6742EZWTA2	null
TMS320C6748EZWT4	null
TMS320C6746EZWTA3	null
TMS320C6748EZWT3	null
AM1802EZWTD3	null
AM1802EZCED3	null
TMS320C6746EZCEA3	null
OMAPL138EZWT3	null
TMS320C6748EZWTD4	null
TMS320C6748EZWTD4E	null
OMAPL138EZCEA3	null
OMAPL138EZWTA3	null
AM1808EZWT4	null
AM1808EZCE4	null
AM1808EZWT3	null

Technical details of this Product Change follow on the next page(s).

PCI	PCN Number: 20160609000				F	PCN Da	ate:	07/01/	2016					
Titl	Title: Qualification of 100% Cu wire bonding on select nfBGA Devices													
Cus	stome	r Conta	ct: P	CN Ma	Manager Dept: Quality Services									
Pro	pose	d 1 st Shi	ip Date	:=	10/01	L/20	16	Est	imated Ava		mple oility:		provide ole reque	
Cha	ange 1	Гуре:									_	-	•	
	Asser	mbly Site	e				Design				Wafei	r Bum _l	p Site	
\boxtimes		mbly Pro					Data SI	heet			Wafei	r Bum _l	p Materi	al
\boxtimes		mbly Ma						mber change	е				p Proces	S
		anical S	•				Test Si					r Fab S		
	Packi	ng/Ship	ping/La	beling	g		Test Pr	ocess					Materials	5
											Wafei	r Fab F	Process	
			_				PCN	Details						
Des	scripti	ion of C	hange:											
				ased t	to anı	noui	nce the d	qualification (of 100%	6 Cu	bondi	ng for	the nfB	GA
dev	ices lis	sted belo	ow.											
														İ
Current Bonding Nev			w Bon	ding										
		Wire	Type/D	Diam	C	0.80mil Au, 0.80mil Cu		C	0.70mil Cu					
		Mold	Mold Compound 42085		515			42218	05					
Reason for Change:														
 1) 2) 	Continuity of supply. 1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties 2) Maximize flexibility within our Assembly/Test production sites. 3) Cu is easier to obtain and stock													
Ant	Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):													
Nor	None													
Anticipated impact on Material Declaration														
		npact to rial Deck			Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the <u>TI ECO website</u> .					n				
Cha	anges	to proc	luct ide	entifi	catio	n re	esulting	from this F	PCN:					
Nor	ne													

Product Affected:			
AM1802EZCED3	AM1810EZWTA3	OMAPL138EZWTA3	TMS320C6746EZWTD4
AM1802EZWTD3	M10MAPL138EZCER	OMAPL138EZWTA3CS	TMS320C6748EZCE3
AM1806EZCE3	OMAPL132EZWT2	OMAPL138EZWTA3E	TMS320C6748EZCE4
AM1806EZCE4	OMAPL132EZWTA2	OMAPL138EZWTA3R	TMS320C6748EZCEA3
AM1806EZCEA3	OMAPL132EZWTA2E	OMAPL138EZWTA4	TMS320C6748EZCEA3E
AM1806EZCED4	OMAPL132EZWTA2R	OMAPL138EZWTD4	TMS320C6748EZCED4
AM1806EZWT3	OMAPL138EZCE3	OMAPL138EZWTD4E	TMS320C6748EZCED4E
AM1806EZWT4	OMAPL138EZCE4	TMS320C6742EZCE2	TMS320C6748EZWT3
AM1806EZWTD4	OMAPL138EZCEA3	TMS320C6742EZWT2	TMS320C6748EZWT3CS
AM1808EZCE3	OMAPL138EZCEA3D	TMS320C6742EZWTA2	TMS320C6748EZWT4
AM1808EZCE4	OMAPL138EZCEA3E	TMS320C6746EZCE3	TMS320C6748EZWTA3
AM1808EZCEA3	OMAPL138EZCEA3R	TMS320C6746EZCEA3	TMS320C6748EZWTA3E
AM1808EZCED4	OMAPL138EZCED4	TMS320C6746EZCED4	TMS320C6748EZWTD4
AM1808EZWT3	OMAPL138EZCED4E	TMS320C6746EZWT3	TMS320C6748EZWTD4E
AM1808EZWT4	OMAPL138EZCEML	TMS320C6746EZWT3CS	TNETV138EINZWT4
AM1808EZWTA3	OMAPL138EZWT3	TMS320C6746EZWT4	
AM1808EZWTD4	OMAPL138EZWT4	TMS320C6746EZWTA3	

Qualification Report

0.70mil PCC + Dry Compression Mold Technology Qual - Freon 361ZWT nfBGA driver Approve Date 08-Jun-2015

Product Attributes

1 1 Odd CC / LCL 1 Dd CCS				
Attributes	Qual Device: TMS320C6748BZWTA3E	QBS Product Reference: 771570ZCE365	QBS Package Reference: TNETV1061ZWC	
Assembly Site	PHI (TIPI)	PHI (TIPI)	PHI (TIPI)	
Package Family	NFBGA	NFBGA	NFBGA	
Wafer Fab Supplier	UMC FAB12I	UMCI	DMOS6	
Wafer Fab Process	1218C021.M6	1218C021.M7	1533C035.15C2	

⁻ QBS: Qual By Similarity

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: TMS320C6748BZWTA3E	QBS Product Reference: 771570ZCE365	QBS Package Reference: TNETV1061ZWC
PC	PreCon Level 3	3XIR/260C	3/960/0	3/870/0	-
PC	PreCon Level 4	3XIR/260C	-	-	3/1080/0
HTOL	Life Test, 125C	1000hrs/125C	-	3/240/0	3/240/0
ТНВ	Biased Temperature and Humidity, 85C/85%RH	1000hrs/85C/85%RH	3/78/0	-	-
UHAST	Unbiased HAST 110C/85%RH	264hrs/110C/85%RH	3/240/0	3/240/0	3/300/0
TC	Temperature Cycle, -55/125C	1000cyc/-55C/125C	3/240/0	3/240/0	3/240/0
HTSL	High Temp Storage Bake 150C	1000hrs/150C	3/240/0	3/300/0	3/179/0
WBP	Bond Strength	76 ball bonds, min. 3	3/Pass	-	3/228/0

⁻ Qual Device TMS320C6748BZWTA3E is qualified at LEVEL3-260CG

Туре	Test Name / Condition	Duration	Qual Device: TMS320C6748BZWTA3E	QBS Product Reference: 771570ZCE365	QBS Package Reference: TNETV1061ZWC
		units			
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	3/Pass	3/Pass	3/Pass
PD	Physical Dimensions	(per mechanical drawing)	-	-	1/10/0
YLD	FTY and Bin Summary	-	3/Pass	-	3/Pass

⁻ Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

Qualification Report

0.70mil PCC + Dry Compression Mold Technology Qual - DM365 338ZCE nfBGA driver Approve Date 19-Jun-2015

Product Attributes

Attributes	Qual Device: 771570ZCE365	QBS Package Reference: TMS320C6748BZWTA3E
Assembly Site	PHI (TIPI)	PHI (TIPI)
Package Family	NFBGA	NFBGA
Wafer Fab Supplier	UMCI	UMC FAB12I
Wafer FAB Process	1218C021.M7	1218C021.M6

⁻ QBS: Qual By Similarity

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: 771570ZCE365	QBS Package Reference: TMS320C6748BZWTA3E
HTOL	Life Test, 125C	1000hrs/125C	3/240/0	
HTSL	High Temp Storage Bake 150C	1000hrs/150C	3/300/0	3/240/0
HTSL	High Temp Storage Bake 150C	1500hrs/150C		3/240/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	3/Pass	3/Pass
PC	PreCon Level 3	3XIR/260C	3/870/0	3/960/0
TC	Temperature Cycle, -55/125C	1000cyc/-55C/125C	3/240/0	3/240/0
TC	Temperature Cycle, -55/125C	1500cyc-ext/-55C/125C		3/210/0
THB	Biased Temperature and Humidity, 85C/85%RH	1000hrs/85C/85%RH		3/78/0
THB	Biased Temperature and Humidity, 85C/85%RH	2500hours/85C/85%RH		3/77/0
UHAST	Unbiased HAST 110C/85%RH	264hrs/110C/85%RH	3/240/0	3/240/0

⁻ Qual Device 771570ZCE365 is qualified at LEVEL3-260C

Туре	Test Name / Condition	Duration	Qual Device: 771570ZCE365	QBS Package Reference: TMS320C6748BZWTA3E
WBP	Bond Strength	76 ball bonds, min. 3 units		3/Pass
YLD	FTY and Bin Summary	-		3/Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at Tl's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com